

General Description

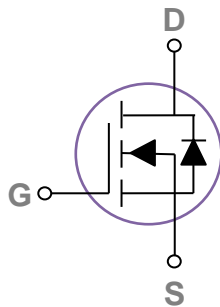
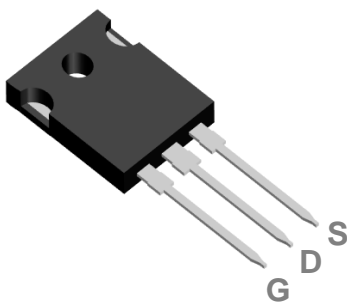
These N-Channel enhancement mode power field effect transistors are planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply

BVDSS	RDSON	ID
200V	80mΩ	30A

Features

- 200V,30A, $R_{DS(ON)} = 80m\Omega @ V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

TO247 Pin Configuration



Applications

- Networking
- Load Switch
- LED applications
- Quick Charger

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	200	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	30	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	19	A
I_{DM}	Drain Current – Pulsed ¹	120	A
EAS	Single Pulse Avalanche Energy ²	800	mJ
IAS	Single Pulse Avalanche Current ²	40	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	195	W
	Power Dissipation – Derate above 25°C	1.56	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	0.64	$^\circ\text{C/W}$

Electrical Characteristics (T_J=25 °C, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	200	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =200V, V _{GS} =0V, T _J =25°C	---	---	1	μA
		V _{DS} =160V, V _{GS} =0V, T _J =85°C	---	---	10	μA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =15A	---	64	80	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250μA	1	1.5	2.3	V

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q _g	Total Gate Charge ^{3, 4}	V _{DS} =100V, V _{GS} =10V, I _D =15A	---	49.5	75	nC
Q _{gs}	Gate-Source Charge ^{3, 4}		---	2.9	5	
Q _{gd}	Gate-Drain Charge ^{3, 4}		---	11.5	18	
T _{d(on)}	Turn-On Delay Time ^{3, 4}	V _{DD} =100V, V _{GS} =10V, R _G =3.3Ω I _D =15A	---	8.2	13	ns
T _r	Rise Time ^{3, 4}		---	22.8	35	
T _{d(off)}	Turn-Off Delay Time ^{3, 4}		---	52.6	79	
T _f	Fall Time ^{3, 4}		---	67.6	102	
C _{iss}	Input Capacitance	V _{DS} =100V, V _{GS} =0V, F=1MHz	---	1670	2505	pF
C _{oss}	Output Capacitance		---	133	200	
C _{rss}	Reverse Transfer Capacitance		---	22	33	
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	---	2.85	---	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	30	A
I _{SM}	Pulsed Source Current		---	---	60	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1	V
t _{rr}	Reverse Recovery Time ³	V _R =200V, I _S =10A	---	170	---	ns
Q _{rr}	Reverse Recovery Charge ³	di/dt=100A/μs, T _J =25°C	---	970	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V, V_{GS}=10V, L=1mH, I_{AS}=40A., R_G=25Ω, Starting T_J=25°C.
3. The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.

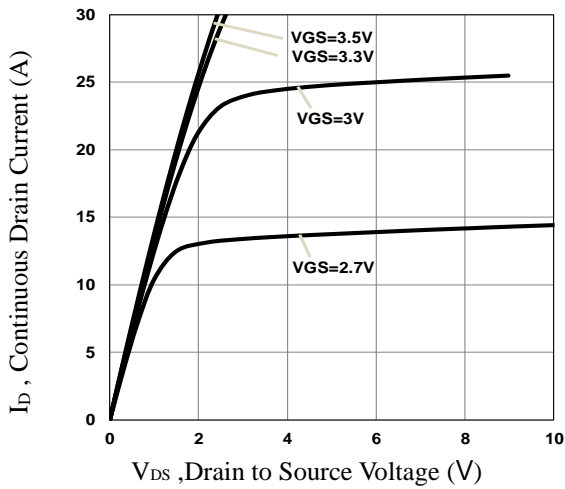


Fig.1 Typical Output Characteristics

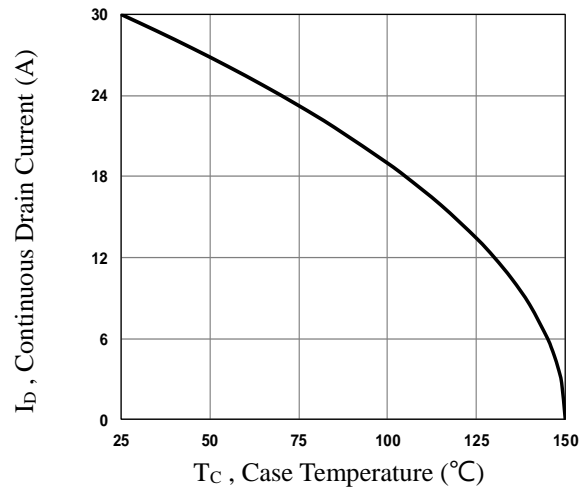


Fig.2 Continuous Drain Current vs. T_c

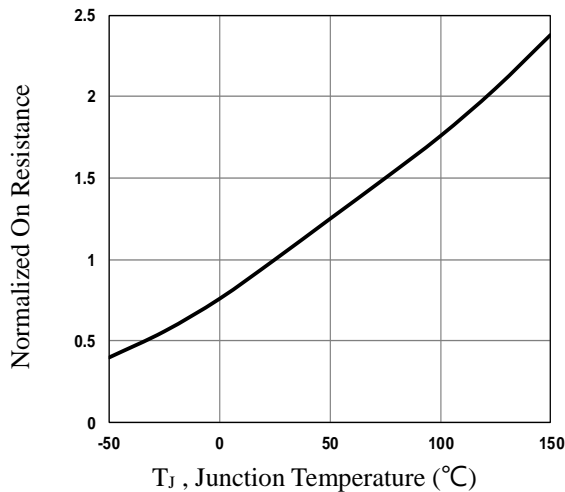


Fig.3 Normalized R_{DS(on)} vs. T_j

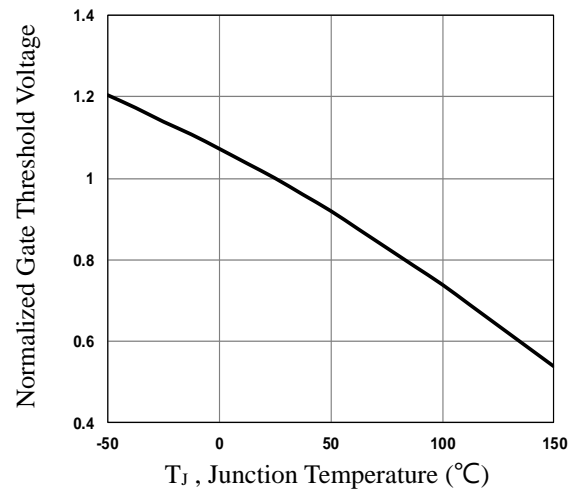


Fig.4 Normalized V_{th} vs. T_j

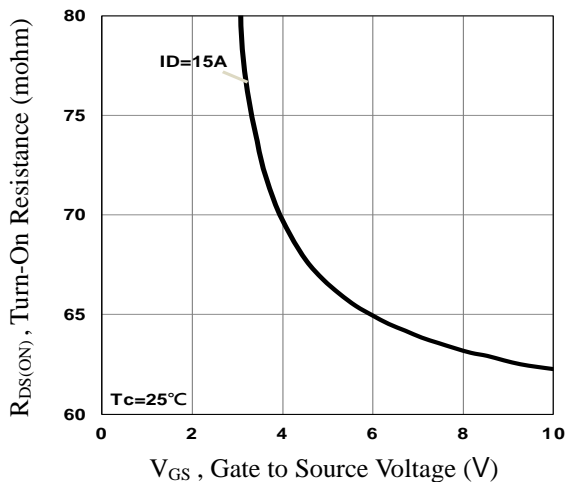


Fig.5 Turn-On Resistance vs. V_{GS}

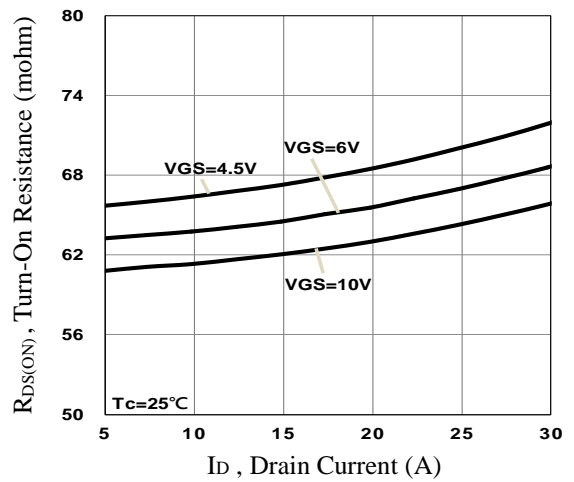


Fig.6 Turn-On Resistance vs. I_D

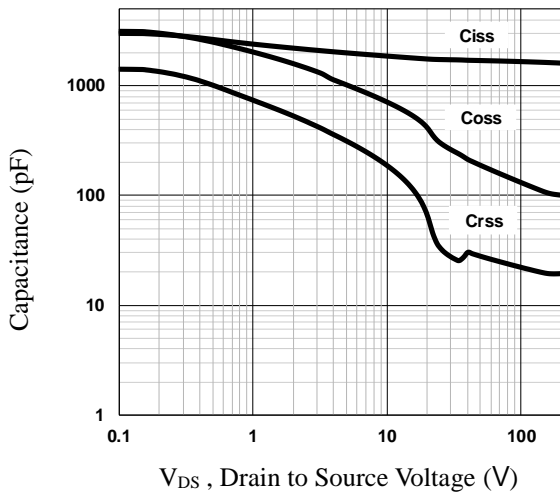


Fig.7 Capacitance Characteristics

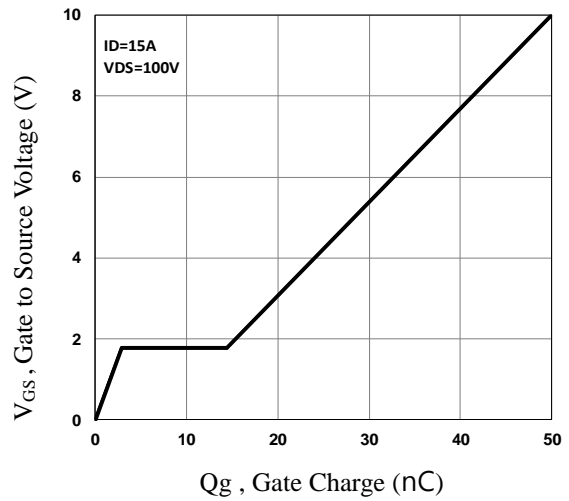


Fig.8 Gate Charge Characteristics

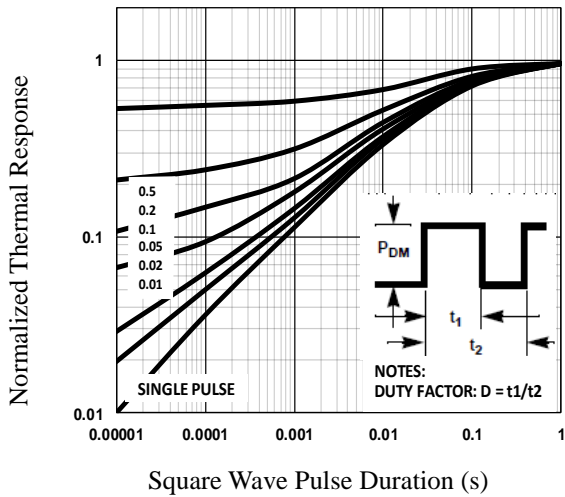


Fig.9 Normalized Transient Impedance

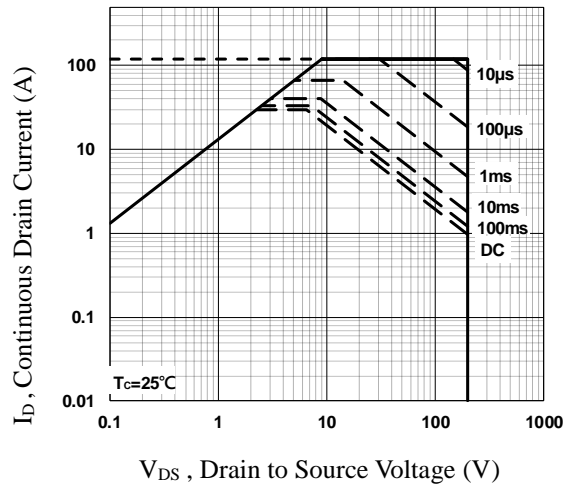


Fig.10 Maximum Safe Operation Area



Fig.11 Switching Time Waveform

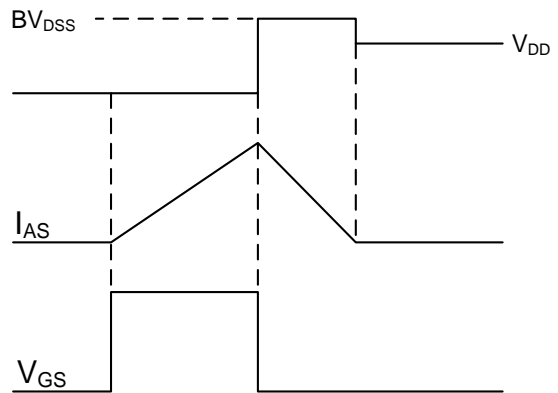
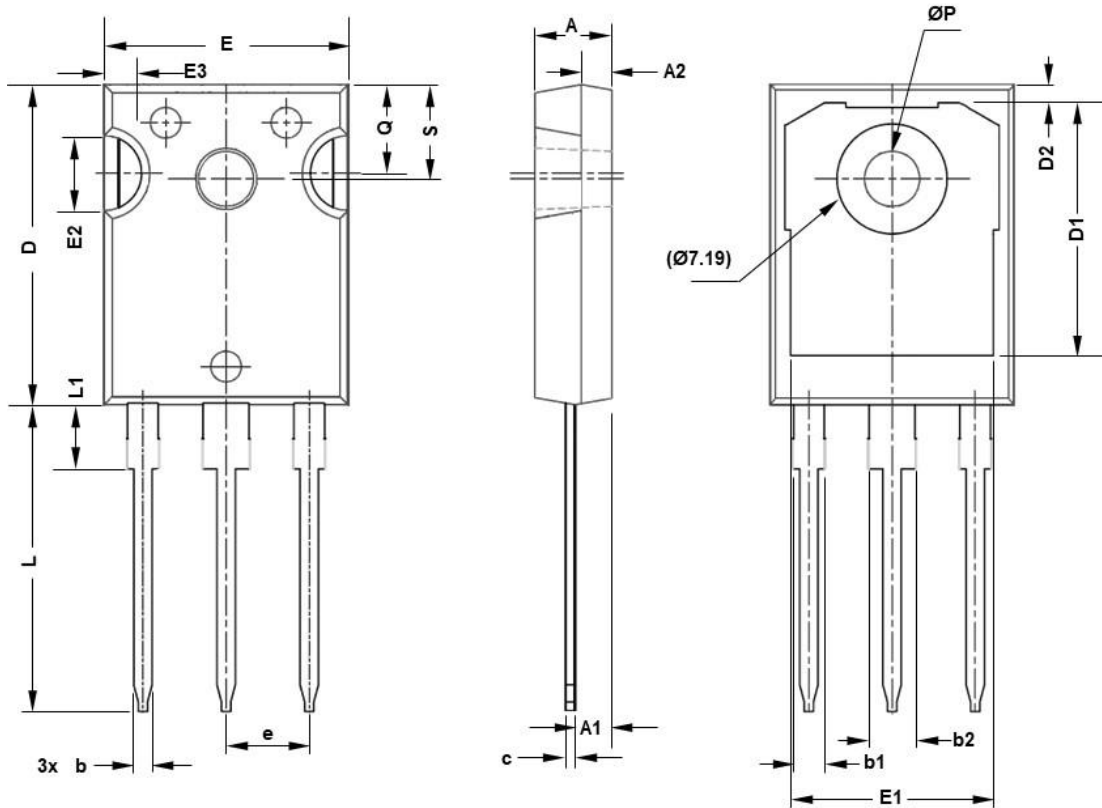


Fig.12 EAS Waveform

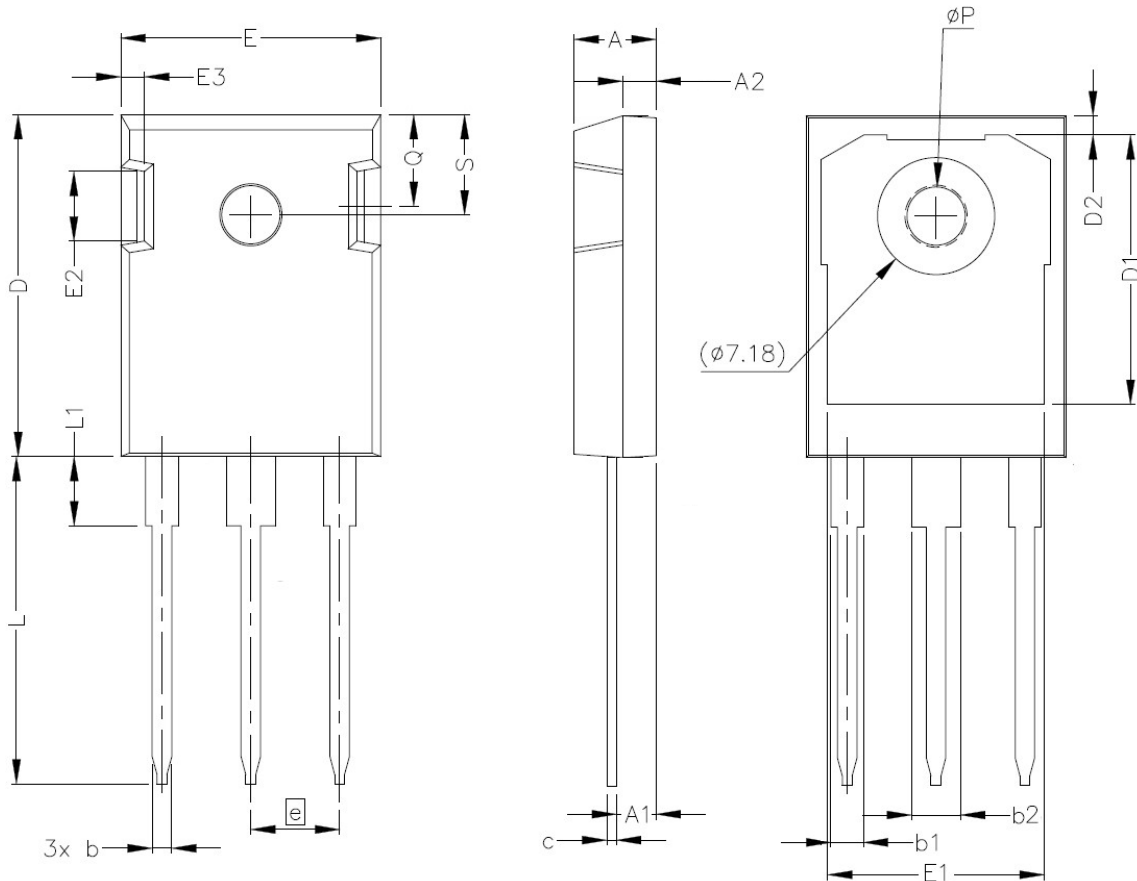
TO247 PACKAGE INFORMATION

VERSION A



SYMBOL	mm		SYMBOL	mm	
	MIN	MAX		MIN	MAX
A	4.83	5.21	E2	4.32	5.49
A1	2.29	2.55	E3	2.15	2.80
A2	1.50	2.49	e	5.44BSC	
b	1.12	1.33	L	19.81	20.32
b1	1.91	2.39	L1	4.10	4.40
b2	2.87	3.22	ΦP	3.56	3.65
C	0.55	0.69	Q	5.39	6.20
D	20.80	21.10	S	6.04	6.30
D1	16.25	17.65			
D2	0.51	1.35			
E	15.75	16.13			
E1	13.46	14.16			

VERSION B



SYMBOL	mm		SYMBOL	mm	
	MIN	MAX		MIN	MAX
A	4.75	5.25	E2	3.70	5.30
A1	2.16	2.66	E3	1.00	2.75
A2	1.75	2.25	e	5.44BSC	
b	1.07	1.35	L	19.52	20.32
b1	1.90	2.41	L1	4.10	4.40
b2	2.87	3.38	ΦP	3.35	3.85
C	0.50	0.70	Q	5.40	6.20
D	20.60	21.40	S	6.15BSC	
D1	16.15	17.65			
D2	0.95	1.35			
E	15.50	16.10			
E1	12.40	13.60			